

Notice of References Cited	Application/Control No. 10/813,330	Applicant(s)/Patent Under Reexamination LEE ET AL.	
	Examiner Caridad M. Everhart	Art Unit 2891	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-6,255,192	07-2001	Dornisch, Dieter	438/430
	C	US-6,696,338	02-2004	Oh et al.	438/253
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	M	US-			

FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

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	U	Nishimura, et al "Relable Submicron Vias Using Aluminum Alloy High Temperature Suptter Filling". 1991 Proc. 8 th International IEEE VLSI Multilevel Interconnection Conf. June 11-12, 1991, Santa Clara, CA pp. 170-176.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.